

N-channel SiC power MOSFET

V_{DSS}	650V
R _{DS(on)} (Typ.)	120m $Ω$
I _D	21A
P_D	103W

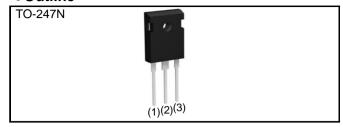
Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

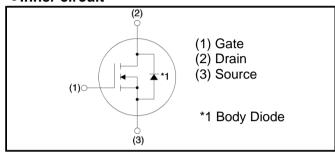
Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

Outline



•Inner circuit



Packaging specifications

	ging opositioations	
	Packing	Tube
	Reel size (mm)	-
Typo	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	30
	Taping code	C11
	Marking	SCT3120AL

● Absolute maximum ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	650	V	
Continuous drain current	T _c = 25°C	I _D *1	21	А
	T _c = 100°C	I _D *1	15	А
Pulsed drain current		I _{D,pulse} *2	52	А
Gate - Source voltage (DC)		V_{GSS}	−4 to +22	V
Gate-Source Surge Voltage (t _{surge} < 300nsec)		V _{GSS_surge} *3	−4 to +26	V
Recommended Drive Voltage		V _{GS_op} *4	0 / +18	V
Junction temperature		T _j	175	°C
Range of storage temperature		T _{stg}	-55 to +175	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R _{thJC}	-	1.12	1.46	°C/W

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol Conditions —		Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	650	-	-	V
		$V_{DS} = 650 V, V_{GS} = 0 V$				
Zero gate voltage drain current	I_{DSS}	T _j = 25°C	-	1	10	μΑ
		T _j = 150°C	-	2	-	
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	I _{GSS} _	$V_{GS} = -4V$, $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V, I_D = 3.33 \text{mA}$	2.7	-	5.6	V
		$V_{GS} = 18V, I_D = 6.7A$				
Static drain - source on - state resistance	R _{DS(on)} *5	T _j = 25°C	-	120	156	mΩ
2.3.0		T _j = 125°C	-	158.4	-	
Gate input resistance	R_{G}	f = 1MHz, open drain	-	18	-	Ω

●Electrical characteristics (T_a = 25°C)

Doromotor	Cumbal	Symbol Conditions		Values		
Parameter	diameter Symbol	Conditions	Min.	Тур.	Max.	Unit
Transconductance	g fs *5	$V_{DS} = 10V, I_D = 6.7A$	-	2.7	-	S
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	460	-	
Output capacitance	C _{oss}	V _{DS} = 500V	-	35	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	16	-	
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V$ to 300V	-	70	-	pF
Turn - on delay time	t _{d(on)} *5	$V_{DD} = 300V, I_D = 6.7A$	-	14	ı	
Rise time	t _r *5	$V_{GS} = 18V/0V$	-	21	-	no
Turn - off delay time	t _{d(off)} *5	$R_L = 45\Omega$	-	23	ı	ns
Fall time	t _f *5	$R_G = 0\Omega$	-	14	ı	
Turn - on switching loss	E _{on} *5	$V_{DD} = 300V, I_{D} = 6.7A$ $V_{GS} = 18V/0V$	-	29		1
Turn - off switching loss	E _{off} *5	$R_G = 0\Omega L=500\mu H$ * E_{on} includes diode reverse recovery	-	3	-	μJ

•Gate Charge characteristics ($T_a = 25$ °C)

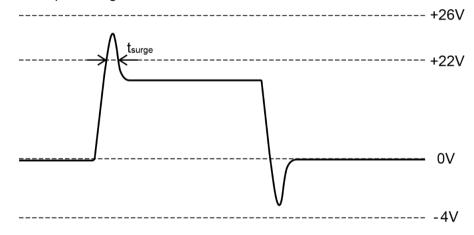
Parameter	Symbol	Conditions	Values			Unit
raiainetei 	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	$V_{DD} = 300V$	-	38	-	
Gate - Source charge	Q _{gs} *5	$I_{D} = 6.7A$	-	11	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 18V	-	13	-	
Gate plateau voltage	V _(plateau)	$V_{DD} = 300V, I_D = 6.7A$	-	9.6	-	V

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions -	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Inverse diode continuous, forward current	l _S *1	T _c = 25°C	-	-	21	А	
Inverse diode direct current, pulsed	I _{SM} *2		-	-	52	А	
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0V, I_{S} = 6.7A$	-	3.2	-	V	
Reverse recovery time	t _{rr} *5	I _F = 6.7A, V _R = 300V di/dt = 1100A/μs	-	13	-	ns	
Reverse recovery charge	Q _{rr} *5		-	35	-	nC	
Peak reverse recovery current	I _{rrm} *5		-	6	-	Α	

^{*1} Limited only by maximum temperature allowed.

^{*3} Example of acceptable Vgs waveform



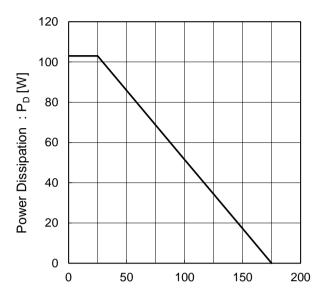
 $^{^{*}4}$ Please be advised not to use SiC-MOSFETs with V_{gs} below 13V as doing so may cause thermal runaway.

*5 Pulsed

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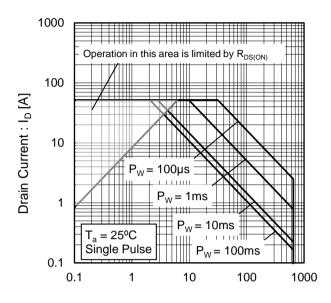
^{*2} PW \leq 10 μ s, Duty cycle \leq 1%

Fig.1 Power Dissipation Derating Curve



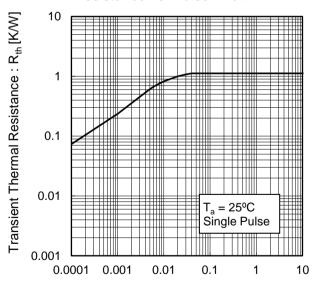
Case Temperature : T_C [° C]

Fig.2 Maximum Safe Operating Area



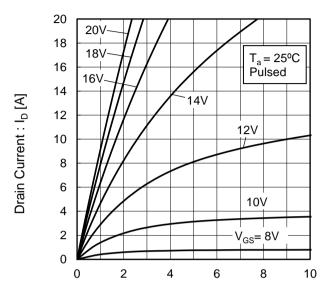
Drain - Source Voltage : V_{DS} [V]

Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



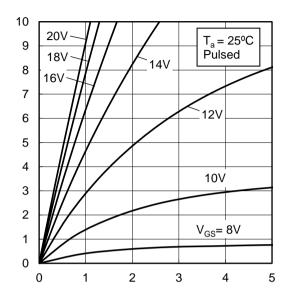
Pulse Width: P_W [s]

Fig.4 Typical Output Characteristics(I)



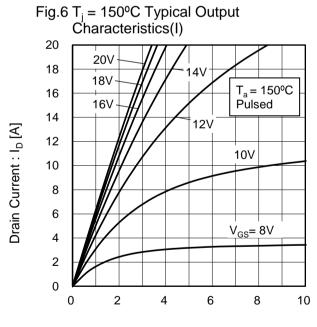
Drain - Source Voltage : V_{DS} [V]

Fig.5 Typical Output Characteristics(II)

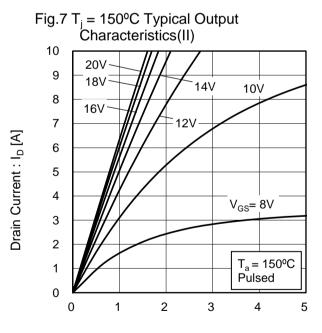


Drain Current: I_D [A]

Drain - Source Voltage : V_{DS} [V]

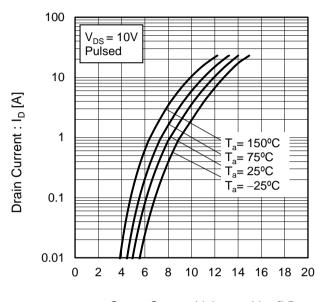


Drain - Source Voltage : V_{DS} [V]



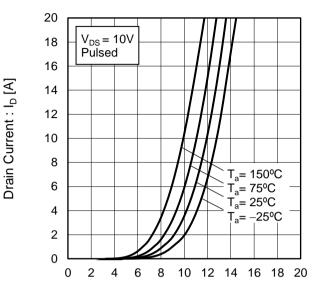
Drain - Source Voltage: V_{DS} [V]

Fig. 8 Typical Transfer Characteristics (I)



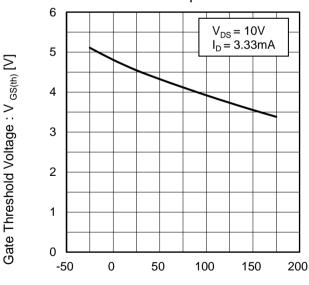
Gate - Source Voltage : V_{GS} [V]

Fig.9 Typical Transfer Characteristics (II)



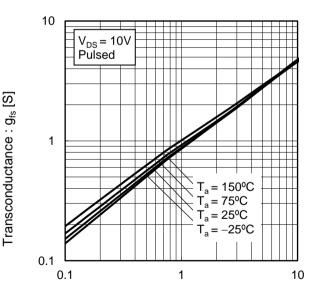
Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

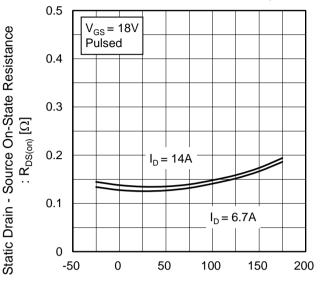
Fig.11 Transconductance vs. Drain Current



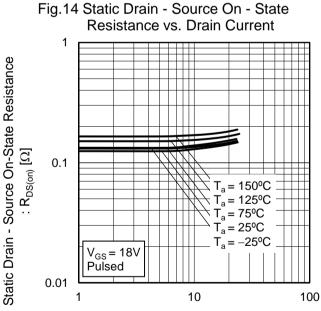
Drain Current : I_D [A]

Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage 0.5 $T_a = 25^{\circ}C$ Static Drain - Source On-State Resistance Pulsed 0.4 0.3 $I_D = 14A$ 0.2 $I_{D} = 6.7A$ 0.1 0 6 10 12 14 16 18 20 22 8

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Gate - Source Voltage : $V_{GS}[V]$ Junction Temperature : $T_i[^0C]$



Drain Current : I_D [A]

Fig.15 Typical Capacitance vs. Drain - Source Voltage 10000 1000 C_{iss} Capacitance: C [pF] $\mathsf{C}_{\mathsf{oss}}$ 100 10 $T_a = 25^{\circ}C$ f = 1MHz $V_{GS} = 0V$

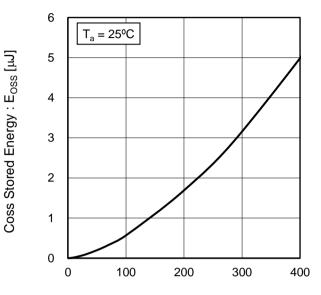
Drain - Source Voltage : V_{DS} [V]

100

1000

10

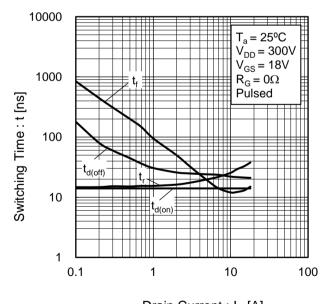
Fig.16 Coss Stored Energy



Drain - Source Voltage : V_{DS} [V]

Fig.17 Switching Characteristics

0.1



Drain Current : I_D [A]

20 $T_a = 25^{\circ}C$

Fig.18 Dynamic Input Characteristics

 $V_{DD} = 300V$ $I_{D} = 6.7A$ Pulsed 15 10 5 0 0 10 20 30 40

Total Gate Charge : Qq [nC]

Gate - Source Voltage : V_{GS} [V]

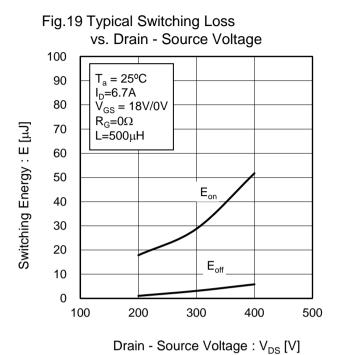
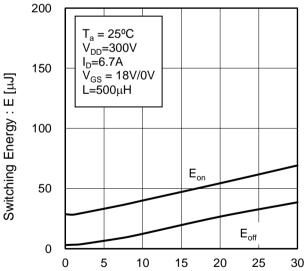


Fig.20 Typical Switching Loss vs. Drain Current 200 $T_a = 25^{\circ}C$ V_{DD}=300V $V_{GS} = 18V/0V$ $R_G = 0\Omega$ Switching Energy : E [μJ] 150 L=500μH 100 E_{on} 50 $\mathsf{E}_{\mathsf{off}}$ 0 5 0 10 15 20

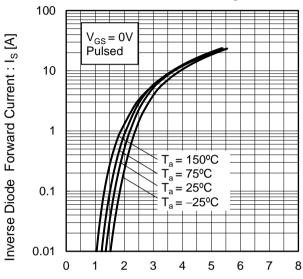
Drain Current: I_D [A]

Fig.21 Typical Switching Loss vs. External Gate Resistance



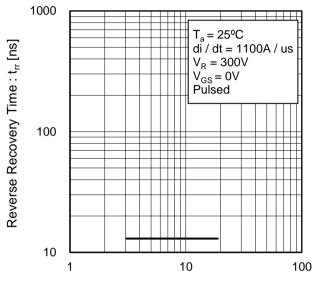
External Gate Resistance : $R_G[\Omega]$

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

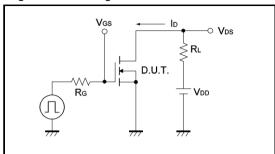


Fig.2-1 Gate Charge Measurement Circuit

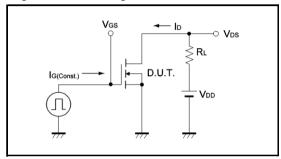


Fig.3-1 Switching Energy Measurement Circuit

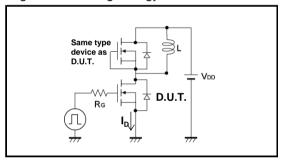


Fig.4-1 Reverse Recovery Time Measurement Circuit Fig.4-2 Reverse Recovery Waveform

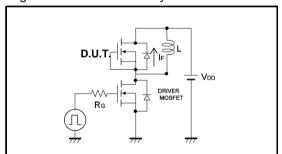


Fig.1-2 Switching Waveforms

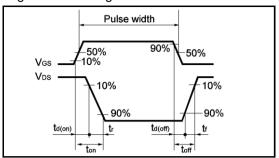


Fig.2-2 Gate Charge Waveform

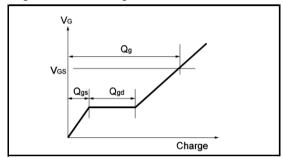
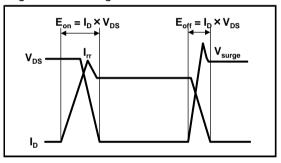
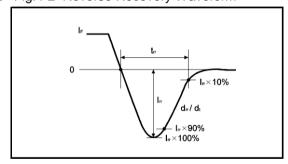


Fig.3-2 Switching Waveforms





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